

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT4578183

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
VIACHSLAV BABAYAN	03/04/2016
DOUGLAS A. BUCHBERGER JR.	03/04/2016
QIWEI LIANG	03/04/2016
LUDOVIC GODET	06/06/2016
SRINIVAS D. NEMANI	03/15/2016
DANIEL J. WOODRUFF	02/25/2016
RANDY HARRIS	02/25/2016
ROBERT B. MOORE	02/25/2016
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	APPLIED MATERIALS, INC.
<b>Street Address:</b>	3050 BOWERS AVENUE
<b>City:</b>	SANTA CLARA
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	95054
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	15692087
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(713)623-4846
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	713-623-4844
<b>Email:</b>	CRouly@pattersonsheridan.com, PSDocketing@pattersonsheridan.com
<b>Correspondent Name:</b>	PATTERSON & SHERIDAN, LLP
<b>Address Line 1:</b>	24 GREENWAY PLAZA, SUITE 1600
<b>Address Line 4:</b>	HOUSTON, TEXAS 77046
<b>ATTORNEY DOCKET NUMBER:</b>	APPM/023506USC01
<b>NAME OF SUBMITTER:</b>	KEITH M. TACKETT
<b>SIGNATURE:</b>	/Keith M. Tackett/

<b>DATE SIGNED:</b>	09/02/2017
<b>Total Attachments: 4</b> source=023506US ASG#page1.tif source=023506US ASG#page2.tif source=023506US ASG#page3.tif source=023506US ASG#page4.tif	

**ASSIGNMENT FOR APPLICATION FOR PATENT**

WHEREAS:

Names and Addresses of Inventors:

1)	Viachslav BABAYAN 422 Firloch Ave. #2 Sunnyvale, California 94086	2)	Douglas A. BUCHBERGER, Jr. 2076 Vintage Lane Livermore, California 94550
3)	Qiwei LIANG 37800 Freesia Court Fremont, California 94536	4)	Ludovic GODET 299W Washington Ave. Sunnyvale, California 94086
5)	Srinivas D. NEMANI 504 Fern Ridge Court Sunnyvale, California 94087	6)	Daniel J. WOODRUFF 409 Northridge Drive Kalispell, Montana 59901
7)	Randy HARRIS 154 West Valley Acres Kalispell, Montana 59901	8)	Robert B. MOORE 1480 Riverside Road Bigfork, Montana 59911

(hereinafter referred to as Assignors), have invented a certain invention entitled:

**METHOD AND APPARATUS FOR POST EXPOSURE PROCESSING OF PHOTORESIST WAFERS**

for which application for Letters Patent in the United States was filed on January 6, 2016, under Serial No. 14/989,488, executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a conventional, division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.


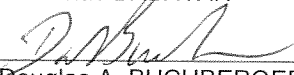

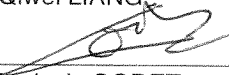
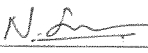
2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest

herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, conventional, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefore and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1)	<u>3/4/16</u> (DATE)	 Viachslav BABAYAN
2)	<u>3/4/14</u> (DATE)	 Douglas A. BUCHBERGER, Jr.
3)	<u>3/4/16</u> (DATE)	 Qiwei LIANG
4)	<u>06/06/2016</u> (DATE)	 Ludovic GODET
5)	<u>3/15/16</u> (DATE)	 Srinivas D. NEMANI
6)	_____ (DATE)	_____ Daniel J. WOODRUFF
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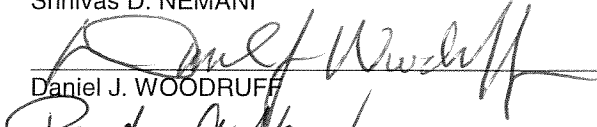
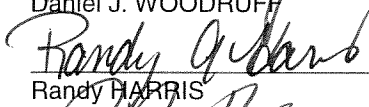

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		Ludovic GODET
5)	_____ (DATE)	_____
		Srinivas D. NEMANI
6)	<u>2/25/16</u> (DATE)	 Daniel J. WOODRUFF
7)	<u>2/25/16</u> (DATE)	 Randy HARRIS
8)	<u>2/25/16</u> (DATE)	 Robert B. MOORE